

50929 U.S. PAT.
09736864
12/14/00

Class	Subclass	ISSUE CLASSIFICATION

PATENT NUMBER

U.S. UTILITY Patent Application

HKM O.I.P.E. SCANNED <u>321</u> Q.A. <u>HT</u>	PATENT DATE
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APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/736864	F	257	737	2817 2345	Chu

APPLICANTS

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TITLE

Interconnection substrate having metal columns covered by a resin film, and manufacturing method thereof

PTO-2040
12/89

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS Sheets Drawg. Fig. Drawg. Print Fig.		<input type="checkbox"/> AIMS ALLOWED	
			Total Claims	Print Claim for O.G.
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